

ALD precursors	Note
TMA TiCl4	For Al2O3 films For TiO2 films
Electron beam evaporator pellets	Note
Al Cr Cu Ni Ti	For Lesker EBE1 and EBE2 tools
Etchants	Note
Al etchant Buffered oxide etchant 7:1 (BoE) Cr etchant Cu etchant	https://www.alfa.com/en/catalog/044581/ https://www.alfa.com/en/catalog/044582/ https://www.alfa.com/en/catalog/044583/
Liquid chemicals	Note
Acetone Hydrochloric acid (HCl) Hydrofluoric acid 49% (HF) Hydrogen peroxide 30% Isopropyl alcohol (IPA) Methanol Nanostrip Sulfuric acid (H2SO4)	
Photoresists	Note
HMDS adhesion promoter AZ P4620 Shipley 1818 AZ 5214 950 PMMA A4 494 PMMA A4 PGMEA	For DRIE For Suss and EVG 610 mask aligners For Suss and EVG 610 mask aligners For electron beam lithography For electron beam lithography
Nanoscribe resins	Note
IP-Visio Photoresist IP-Q Photoresist IP-Dip Photoresist IP-L Photoresist IP-S Photoresist	
Lithography developers and strippers	Note
TMAH 25% in water EBR-10A developer SU-8 developer AZ 400T stripper AZ developer 1:1 AZ 300 MIF developer AZ 726 MIF developer AZ 400K (1:4) developer MIBK/IPA developer MIF-319 developer KAM Remover PG	SU-8 developer
Sputter Targets	Note
Au	For Cressington sputter coater
Al Cr Cu Ni Ti	For Lesker PVD75 DC tool
SiO2	For Lesker PVD75 RF tool
Al Al2O3 Cu Hf Ir NbO2 Nb2O5 Pt Si SiO2 Ta Ti TiN	For Clustex

TiO2
Ru
V2O5
VO2
W